

METHOD OF FORMING A SEMICONDUCTOR PACKAGE AND LEADFRAME
THEREFOR

5 Abstract of the Disclosure

A method of forming a leadframe and a semiconductor package using the leadframe facilitates selectively forming leads for the package. The leadframe is formed with a first portion of the leads extending from a panel of the leadframe into a molding cavity section of the leadframe. After encapsulation, a portion of the leadframe panel is used to form a second portion of the leads that is external to the package body.

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